

Features

- Split Gate Trench MOSFET Technology
- Low R_{DS(on)} & FOM
- Low C_{rss}
- Extremely Low Switching Loss
- · Excellent Stability and Uniformity
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

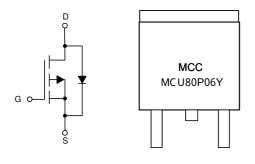
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 20°C/W Junction to Ambient(t≤10S)⁽²⁾
- Thermal Resistance: 50°C/W Junction to Ambient(Steady-State) (2)
- Thermal Resistance: 1.04°C/W Junction to Case(Steady-State)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	-60	V
Gate-Source Volltage	V _{GS}	±18	V
Continuous Drain Current	I _D	-80	Α
Pulsed Drain Current (3)	I _{DM}	-320	Α
Total Power Dissipation ⁽⁴⁾	P _D	120	W
Single Pulsed Avalanche Energy ⁽⁵⁾	E _{AS}	400	mJ

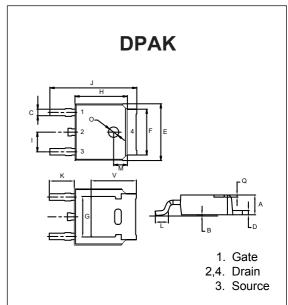
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_{D} is based on max. junction temperature, using junction-case thermal resistance.
- 5. V_{DD} =-60V, R_{G} =25 Ω , L=2mH, I_{AS} =20A.

Internal Structure and Marking Code



P-CHANNEL MOSFET



DIMENSIONS					
DIM	INCHES		MM		NOTE
DIM	MIN	MAX	MIN	MAX	NOTE
Α	0.087	0.094	2.20	2.40	
В	0.000	0.005	0.00	0.13	
С	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
Е	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
Н	0.236	0.244	6.00	6.20	
ı	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.049	0.067	1.25	1.70	
М	0.063		1.60		TYP.
0	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.3	35	TYP.

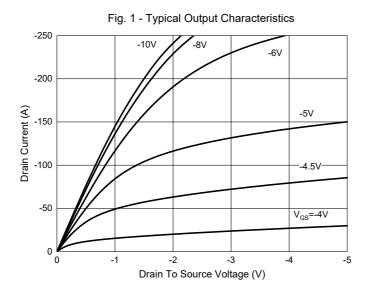


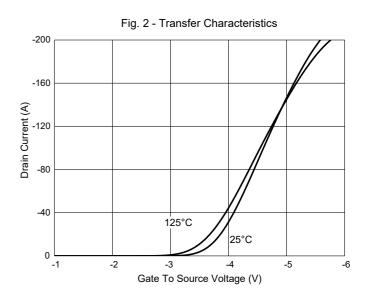
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

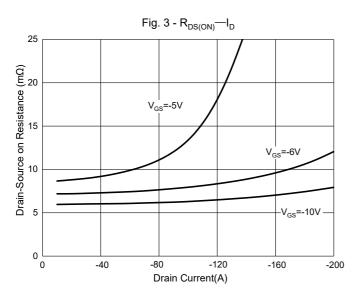
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Static Characteristics				1		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-60			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±18V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V, V _{GS} =0V			-1	μA
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-2	-2.7	-4	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =-10V, I _D =-20A		6.4	8.4	mΩ
Gate Resistance	R _g	Drain open, f=1Mhz		21		Ω
Diode Characteristics						
Continuous Body Diode Current	Is				-80	А
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-20A			-1.3	V
Reverse Recovery Time	t _{rr}	L 00A 1// 1/ 500A/w		46		ns
Reverse Recovery Charge	Q _{rr}	I _S =-20A,di/dt=500A/μs		153		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}			5450		
Output Capacitance	C _{oss}	V_{DS} =-30V, V_{GS} =0V,f=1MHz		900		pF
Reverse Transfer Capacitance	C _{rss}			65		
Total Gate Charge	Qg			82		
Gate-Source Charge	Q_{gs}	V _{DS} =-30V,V _{GS} =-10V,I _D =-20A		24		nC
Gate-Drain Charge	Q_{gd}			16.6		
Turn-On Delay Time	t _{d(on)}			12.8		
Turn-On Rise Time	t _r	V _{DS} =-30V, V _{GS} =-10V,		48		<u></u>
Turn-Off Delay Time	t _{d(off)}	$R_G=1.6\Omega, I_D=-20A$		134.1		ns
Turn-Off Fall Time	t _f			155.6		

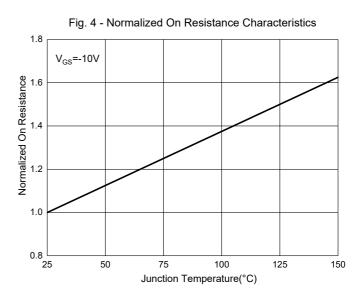


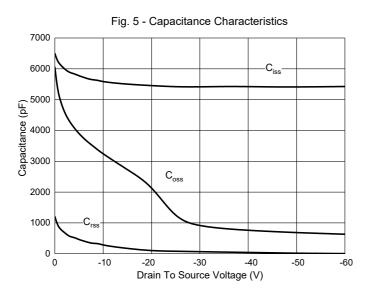
Curve Characteristics

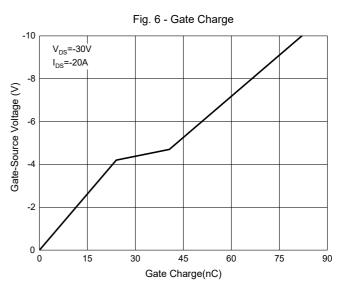














Curve Characteristics

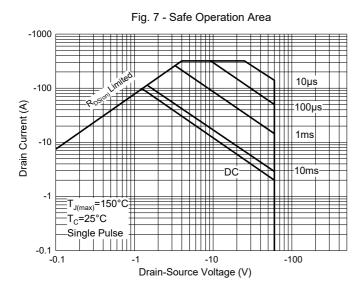
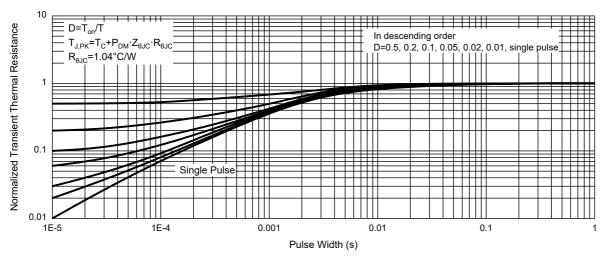


Fig. 8 - Normalized Transient Thermal Impedance



Rev.3-3-04092022 4/5 MCCSEMI.COM



Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel: 2.5Kpcs/Reel	

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